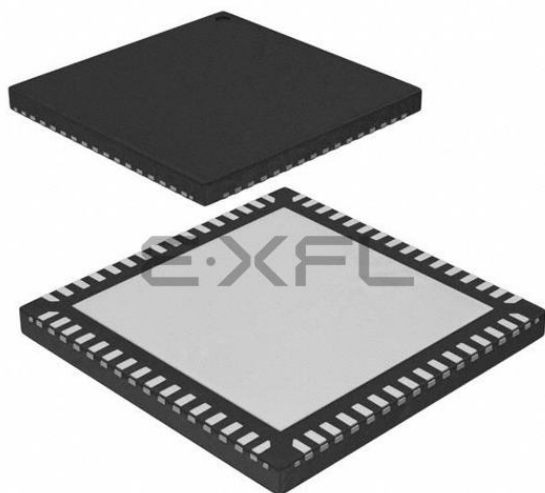




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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	56
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32wg840f64-qfn64

2 System Summary

2.1 System Introduction

The EFM32 MCUs are the world's most energy friendly microcontrollers. With a unique combination of the powerful 32-bit ARM Cortex-M4, with DSP instruction support and floating-point unit, innovative low energy techniques, short wake-up time from energy saving modes, and a wide selection of peripherals, the EFM32WG microcontroller is well suited for any battery operated application as well as other systems requiring high performance and low-energy consumption. This section gives a short introduction to each of the modules in general terms and also shows a summary of the configuration for the EFM32WG840 devices. For a complete feature set and in-depth information on the modules, the reader is referred to the EFM32WG Reference Manual.

A block diagram of the EFM32WG840 is shown in Figure 2.1 (p. 3) .

Figure 2.1. Block Diagram

The logo consists of a stylized blue 'M' followed by a green '3'.

cycles with 256-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

2.1.27 General Purpose Input/Output (GPIO)

In the EFM32WG840, there are 56 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

2.1.28 Liquid Crystal Display Driver (LCD)

The LCD driver is capable of driving a segmented LCD display with up to 8x20 segments. A voltage boost function enables it to provide the LCD display with higher voltage than the supply voltage for the device. In addition, an animation feature can run custom animations on the LCD display without any CPU intervention. The LCD driver can also remain active even in Energy Mode 2 and provides a Frame Counter interrupt that can wake-up the device on a regular basis for updating data.

2.2 Configuration Summary

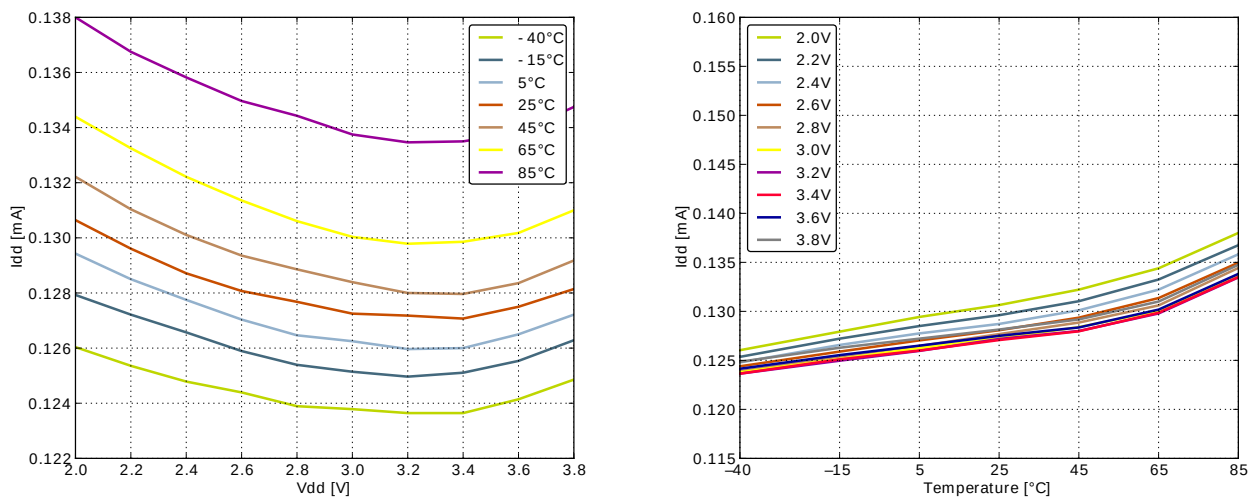
The features of the EFM32WG840 is a subset of the feature set described in the EFM32WG Reference Manual. Table 2.1 (p. 7) describes device specific implementation of the features.

Table 2.1. Configuration Summary

Module	Configuration	Pin Connections
Cortex-M4	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX

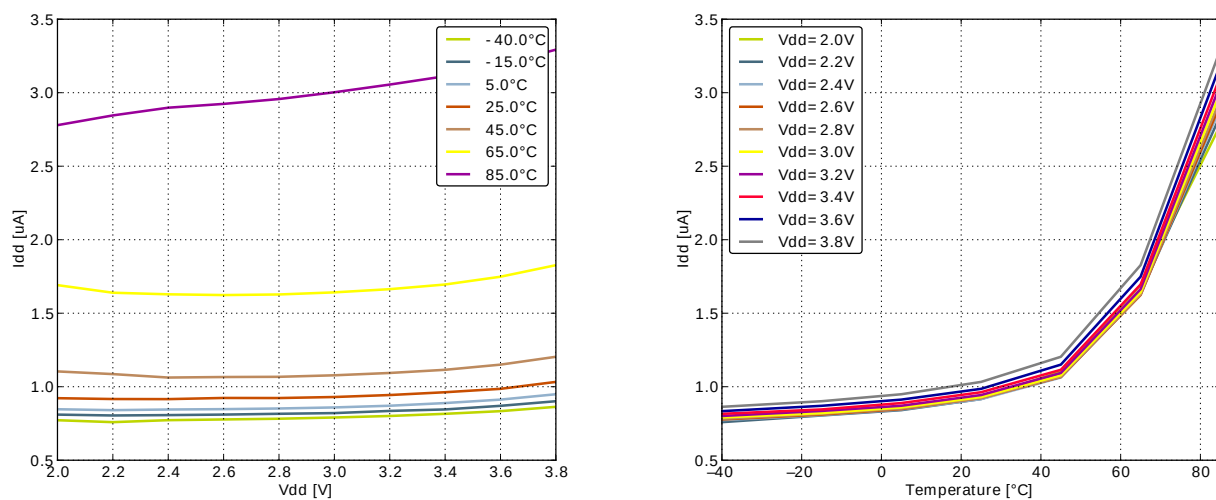
Symbol	Parameter	Condition	Min	Typ	Max	Unit
		1.2 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		271	286	$\mu\text{A}/\text{MHz}$
		1.2 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		275		$\mu\text{A}/\text{MHz}$
I_{EM1}	EM1 current (Production test condition = 14 MHz)	48 MHz HFXO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		63	75	$\mu\text{A}/\text{MHz}$
		48 MHz HFXO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		65	76	$\mu\text{A}/\text{MHz}$
		28 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		64	75	$\mu\text{A}/\text{MHz}$
		28 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		65	77	$\mu\text{A}/\text{MHz}$
		21 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		65	76	$\mu\text{A}/\text{MHz}$
		21 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		66	78	$\mu\text{A}/\text{MHz}$
		14 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		67	79	$\mu\text{A}/\text{MHz}$
		14 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		68	82	$\mu\text{A}/\text{MHz}$
		11 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		68	81	$\mu\text{A}/\text{MHz}$
		11 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		70	83	$\mu\text{A}/\text{MHz}$
		6.6 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		74	87	$\mu\text{A}/\text{MHz}$
		6.6 MHz HFRCO, all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		76	89	$\mu\text{A}/\text{MHz}$
		1.2 MHz HFRCO. all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		106	120	$\mu\text{A}/\text{MHz}$
		1.2 MHz HFRCO. all peripheral clocks disabled, $V_{DD}=3.0\text{ V}$, $T_{AMB}=85^{\circ}\text{C}$		112	129	$\mu\text{A}/\text{MHz}$
I_{EM2}	EM2 current	EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, $V_{DD}=3.0\text{ V}$, $T_{AMB}=25^{\circ}\text{C}$		0.95 ¹	1.7 ¹	μA

Figure 3.7. EM1 Current consumption with all peripheral clocks disabled and HFRCO running at 1.2MHz



3.4.2 EM2 Current Consumption

Figure 3.8. EM2 current consumption. RTC ¹ prescaled to 1kHz, 32.768 kHz LFRCO.



¹Using backup RTC.

3.6 Power Management

The EFM32WG requires the AVDD_x, VDD_DREG and IOVDD_x pins to be connected together (with optional filter) at the PCB level. For practical schematic recommendations, please see the application note, "AN0002 EFM32 Hardware Design Considerations".

Table 3.6. Power Management

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V _{BODextthr-}	BOD threshold on falling external supply voltage		1.74		1.96	V
V _{BODextthr+}	BOD threshold on rising external supply voltage			1.85	1.98	V
V _{PORthr+}	Power-on Reset (POR) threshold on rising external supply voltage				1.98	V
t _{RESET}	Delay from reset is released until program execution starts	Applies to Power-on Reset, Brown-out Reset and pin reset.		163		μs
C _{DECOUPLE}	Voltage regulator decoupling capacitor.	X5R capacitor recommended. Apply between DECOUPLE pin and GROUND		1		μF

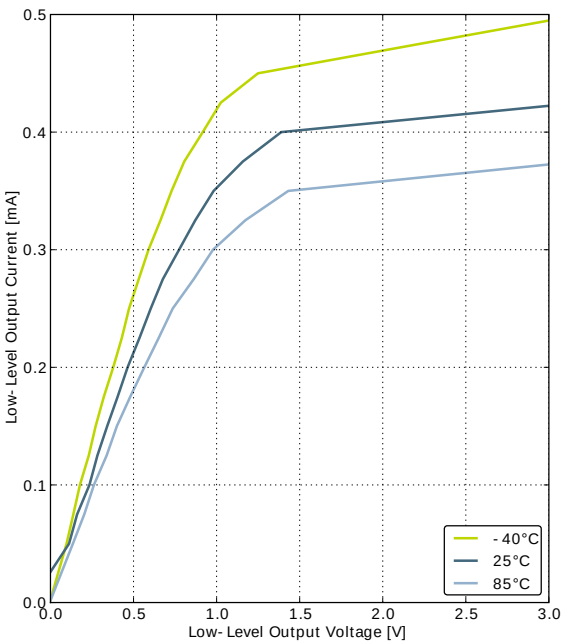
3.7 Flash

Table 3.7. Flash

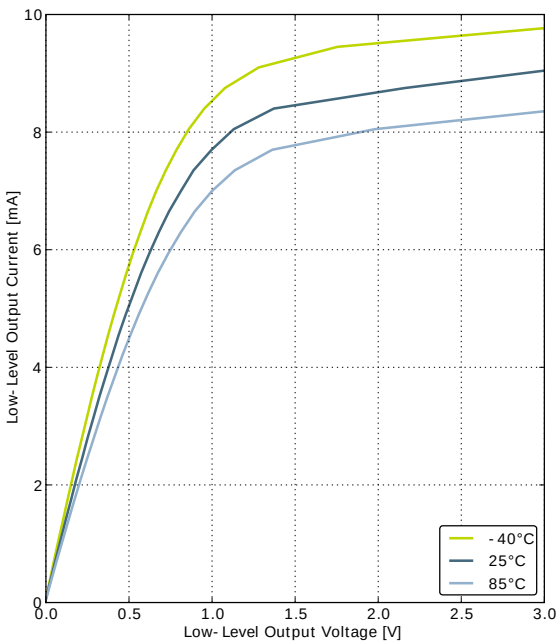
Symbol	Parameter	Condition	Min	Typ	Max	Unit
EC _{FLASH}	Flash erase cycles before failure		20000			cycles
RET _{FLASH}	Flash data retention	T _{AMB} <150°C	10000			h
		T _{AMB} <85°C	10			years
		T _{AMB} <70°C	20			years
t _{W_PROG}	Word (32-bit) programming time		20			μs
t _{PERASE}	Page erase time		20	20.4	20.8	ms
t _{DERASE}	Device erase time		40	40.8	41.6	ms
I _{ERASE}	Erase current				7 ¹	mA
I _{WRITE}	Write current				7 ¹	mA
V _{FLASH}	Supply voltage during flash erase and write		1.98		3.8	V

¹Measured at 25°C

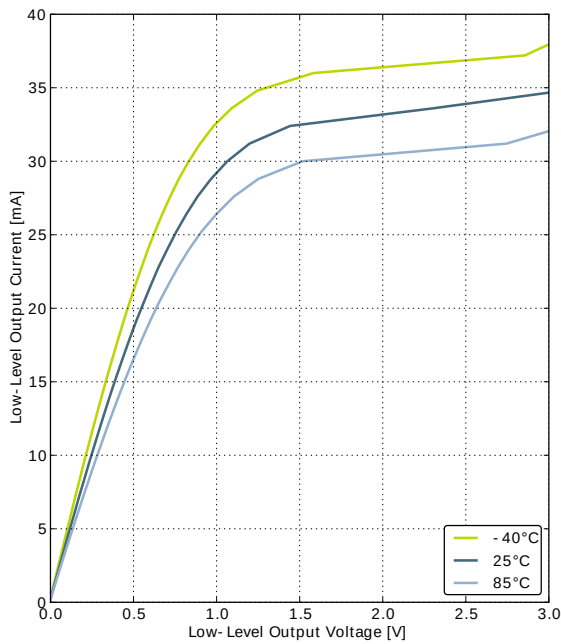
Figure 3.13. Typical Low-Level Output Current, 3V Supply Voltage



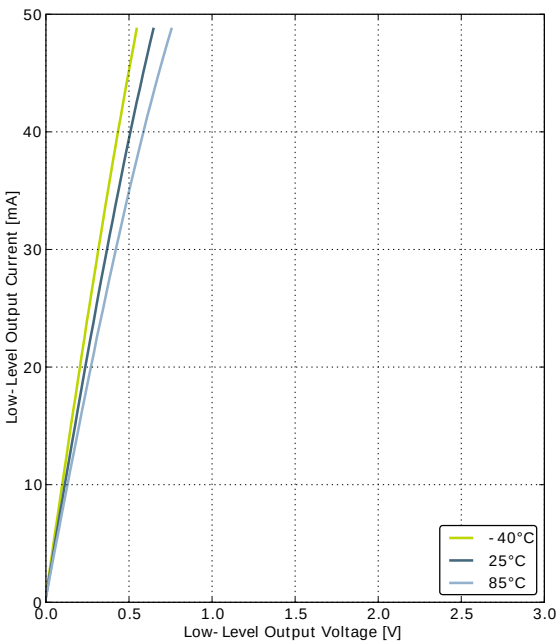
GPIO_Px_CTRL DRIVEMODE = LOWEST



GPIO_Px_CTRL DRIVEMODE = LOW

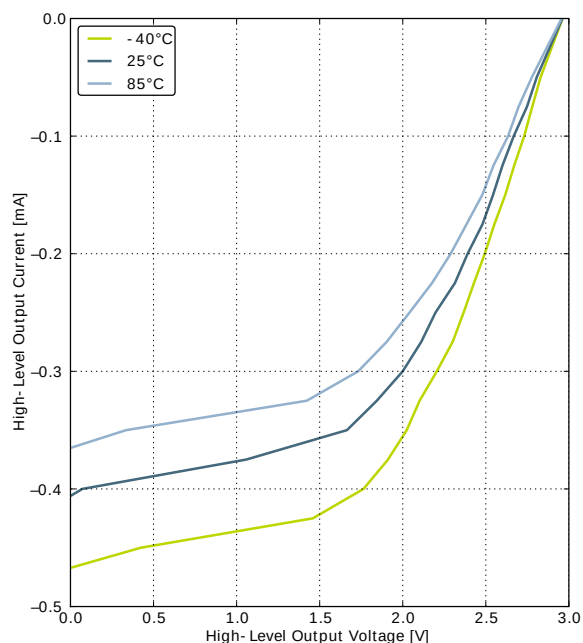


GPIO_Px_CTRL DRIVEMODE = STANDARD

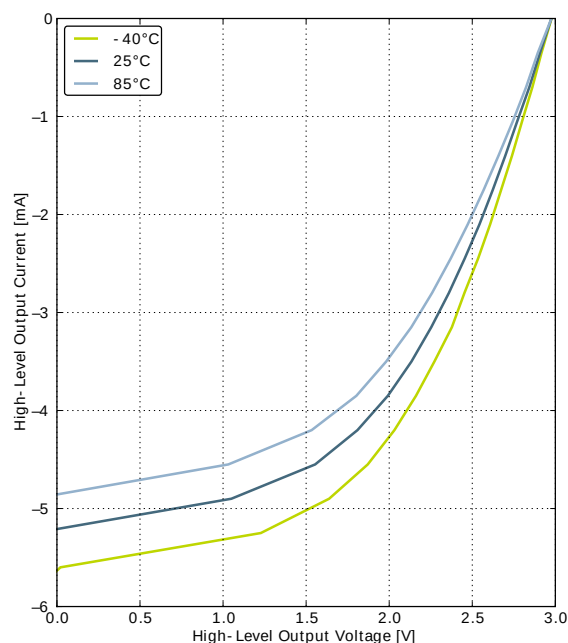


GPIO_Px_CTRL DRIVEMODE = HIGH

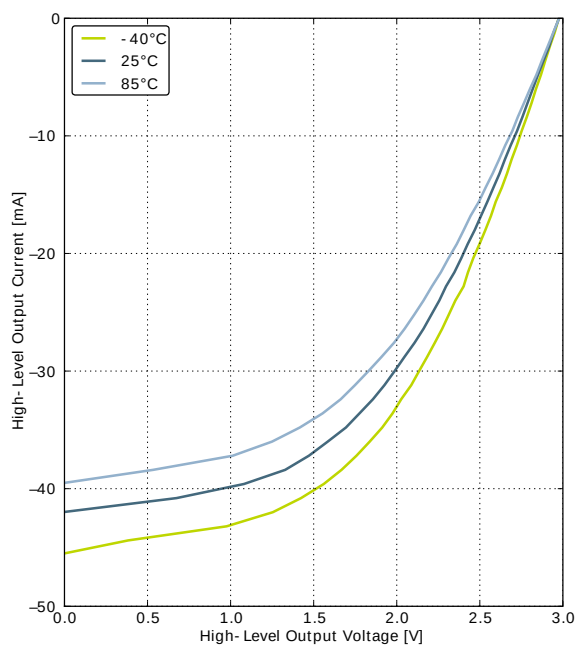
Figure 3.14. Typical High-Level Output Current, 3V Supply Voltage



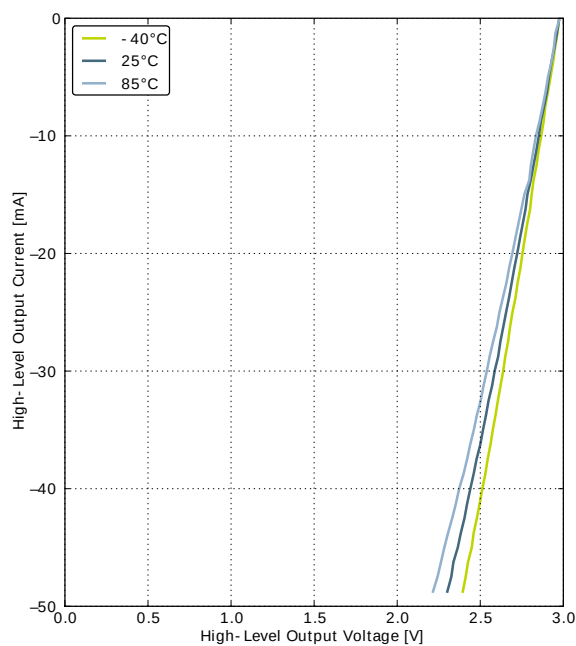
GPIO_Px_CTRL DRIVEMODE = LOWEST



GPIO_Px_CTRL DRIVEMODE = LOW

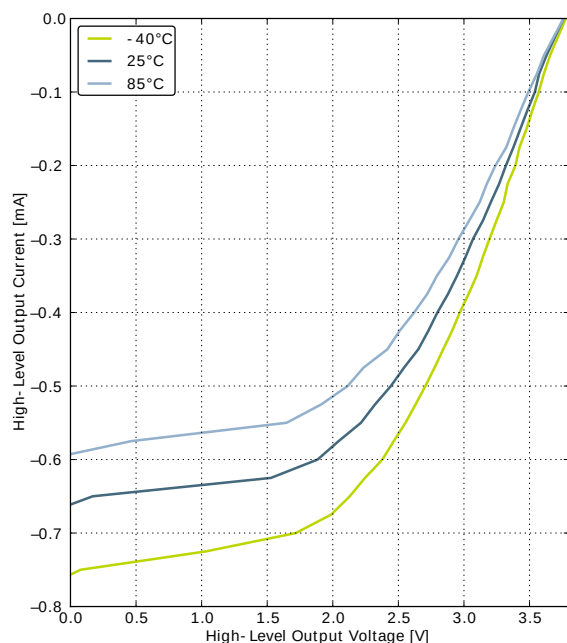


GPIO_Px_CTRL DRIVEMODE = STANDARD

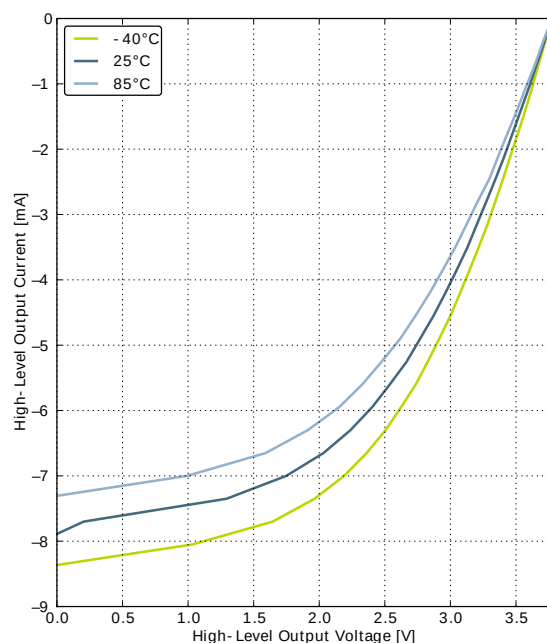


GPIO_Px_CTRL DRIVEMODE = HIGH

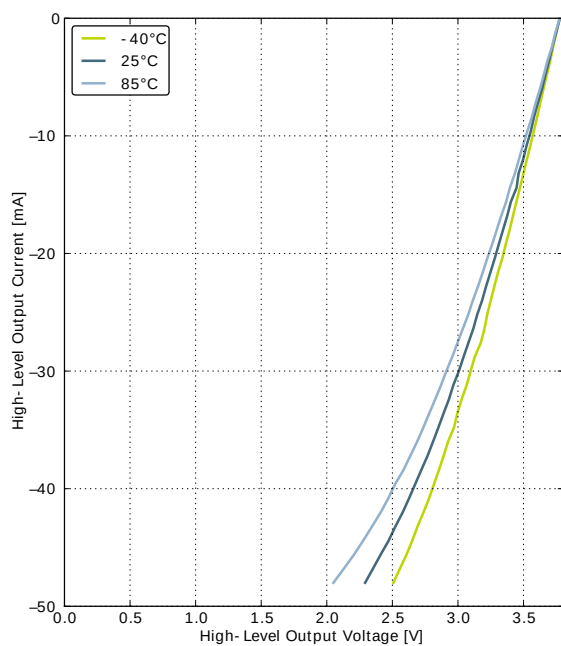
Figure 3.16. Typical High-Level Output Current, 3.8V Supply Voltage



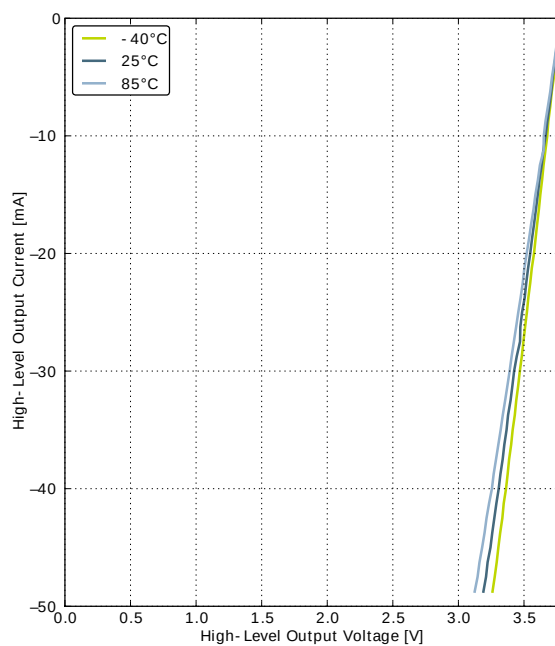
GPIO_Px_CTRL DRIVEMODE = LOWEST



GPIO_Px_CTRL DRIVEMODE = LOW



GPIO_Px_CTRL DRIVEMODE = STANDARD



GPIO_Px_CTRL DRIVEMODE = HIGH

Figure 3.19. Calibrated HFRCO 7 MHz Band Frequency vs Supply Voltage and Temperature

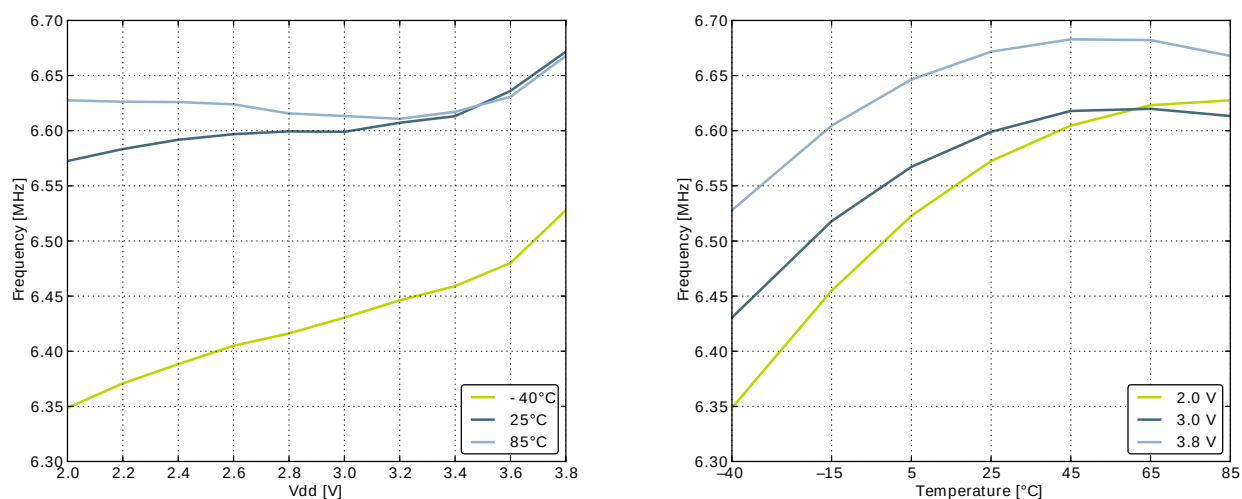


Figure 3.20. Calibrated HFRCO 11 MHz Band Frequency vs Supply Voltage and Temperature

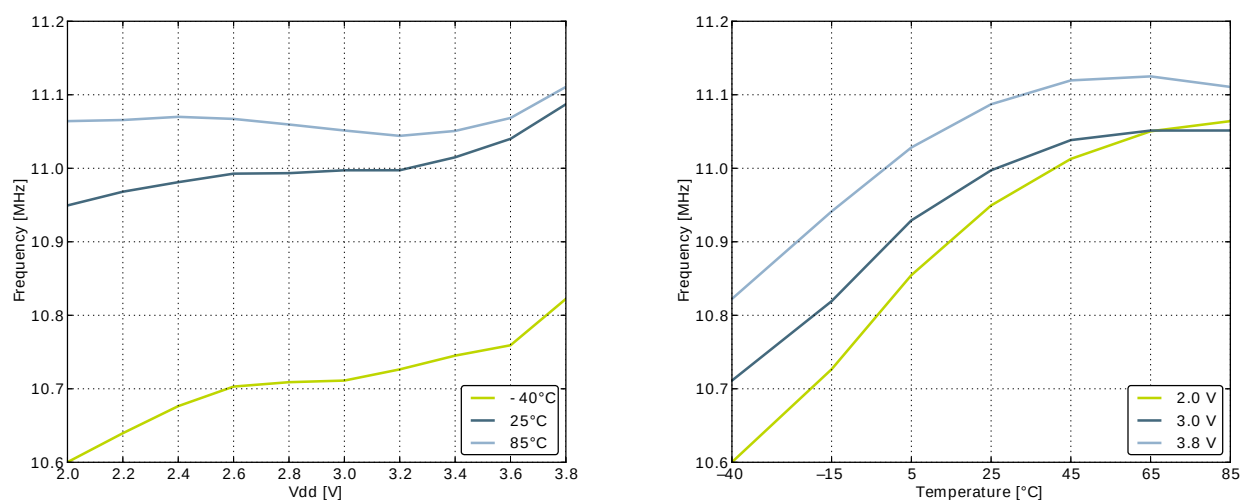


Figure 3.21. Calibrated HFRCO 14 MHz Band Frequency vs Supply Voltage and Temperature

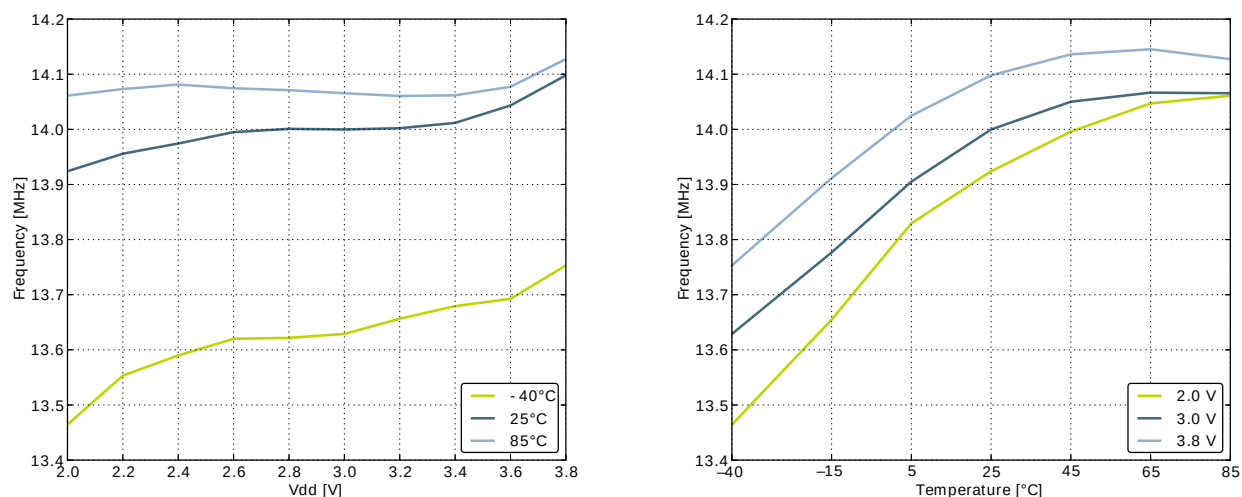


Figure 3.22. Calibrated HFRCO 21 MHz Band Frequency vs Supply Voltage and Temperature

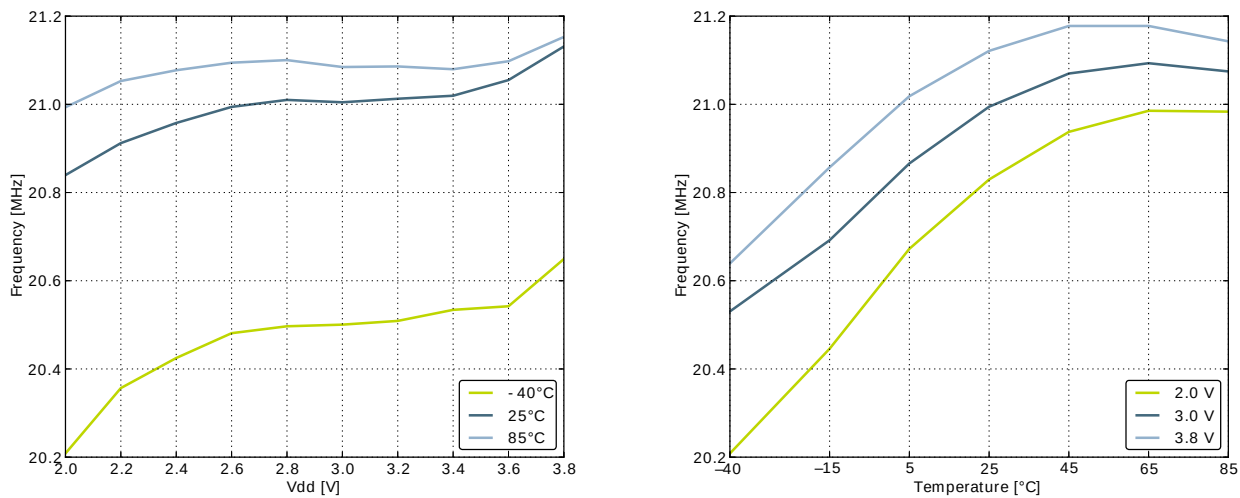
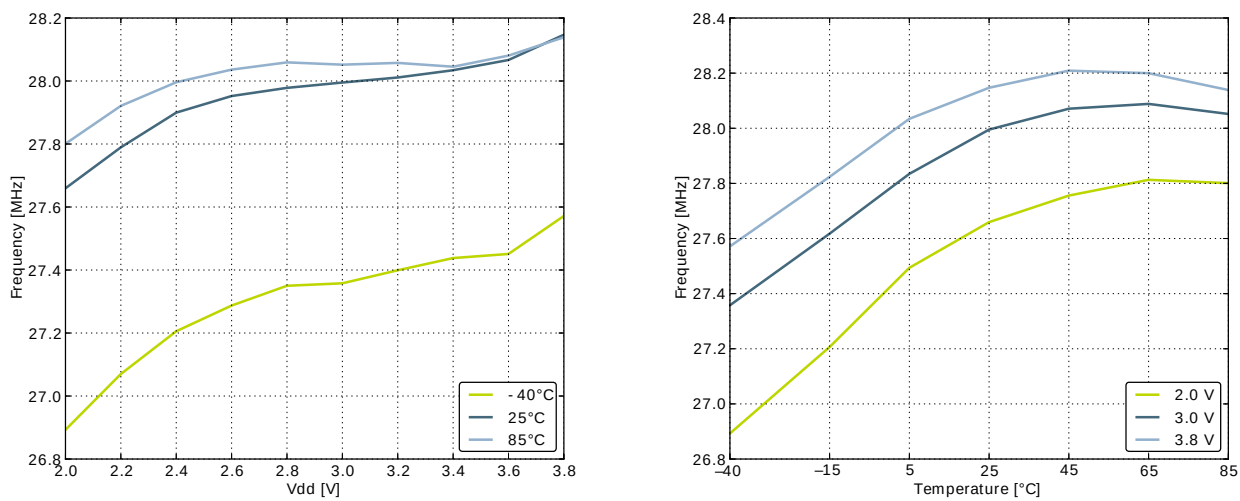


Figure 3.23. Calibrated HFRCO 28 MHz Band Frequency vs Supply Voltage and Temperature



Symbol	Parameter	Condition	Min	Typ	Max	Unit
		1 MSamples/s, 12 bit, differential, internal 2.5V reference		64		dB
		1 MSamples/s, 12 bit, differential, 5V reference		54		dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference		66		dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference		68		dB
		200 kSamples/s, 12 bit, single ended, internal 1.25V reference		61		dB
		200 kSamples/s, 12 bit, single ended, internal 2.5V reference		65		dB
		200 kSamples/s, 12 bit, single ended, V_{DD} reference		66		dB
		200 kSamples/s, 12 bit, differential, internal 1.25V reference		63		dB
		200 kSamples/s, 12 bit, differential, internal 2.5V reference		66		dB
		200 kSamples/s, 12 bit, differential, 5V reference		66		dB
		200 kSamples/s, 12 bit, differential, V_{DD} reference	62	66		dB
		200 kSamples/s, 12 bit, differential, $2xV_{DD}$ reference		69		dB
SFDR _{ADC}	Spurious-Free Dynamic Range (SFDR)	1 MSamples/s, 12 bit, single ended, internal 1.25V reference		64		dBc
		1 MSamples/s, 12 bit, single ended, internal 2.5V reference		76		dBc
		1 MSamples/s, 12 bit, single ended, V_{DD} reference		73		dBc
		1 MSamples/s, 12 bit, differential, internal 1.25V reference		66		dBc
		1 MSamples/s, 12 bit, differential, internal 2.5V reference		77		dBc
		1 MSamples/s, 12 bit, differential, V_{DD} reference		76		dBc
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference		75		dBc
		1 MSamples/s, 12 bit, differential, 5V reference		69		dBc
		200 kSamples/s, 12 bit, single ended, internal 1.25V reference		75		dBc
		200 kSamples/s, 12 bit, single ended, internal 2.5V reference		75		dBc
		200 kSamples/s, 12 bit, single ended, V_{DD} reference		76		dBc

Figure 3.29. ADC Absolute Offset, Common Mode = Vdd / 2

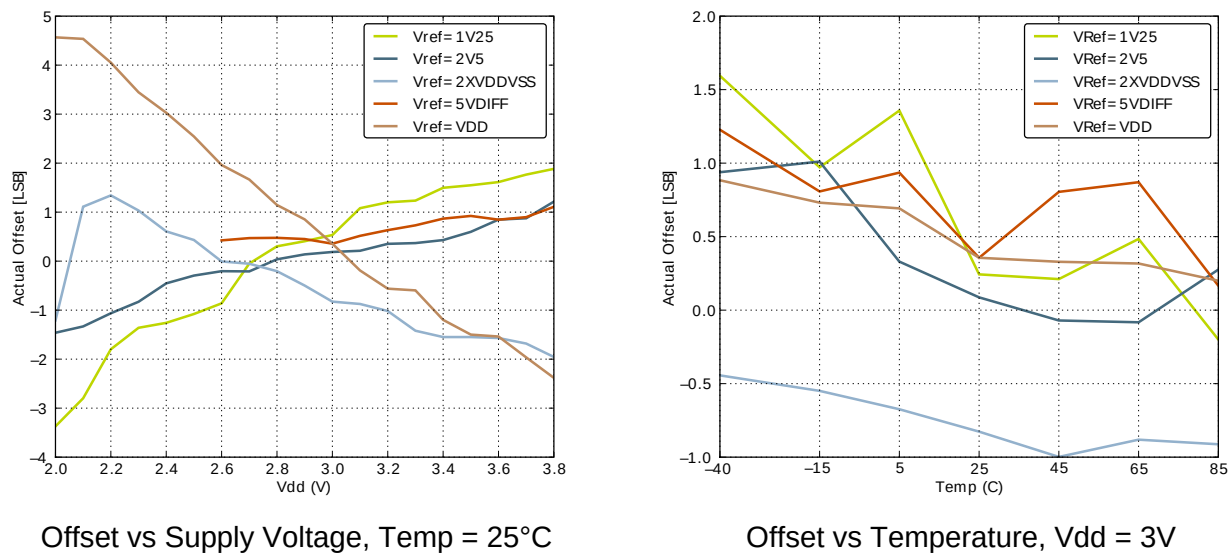


Figure 3.30. ADC Dynamic Performance vs Temperature for all ADC References, Vdd = 3V

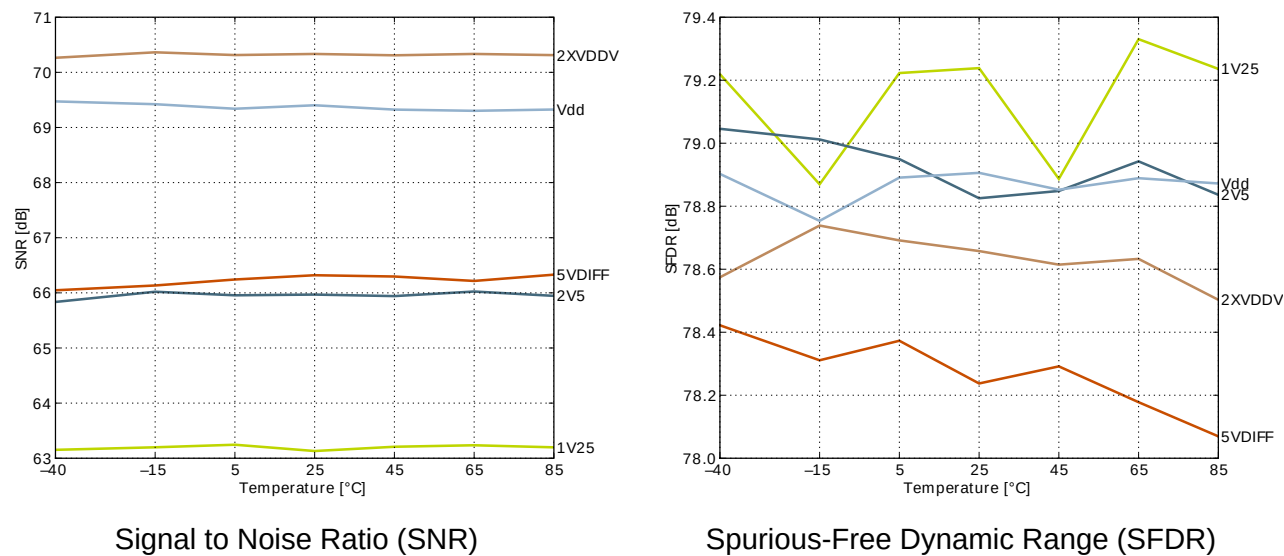


Table 3.23. I2C Fast-mode Plus (Fm+)

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL clock frequency	0		1000 ¹	kHz
t_{LOW}	SCL clock low time	0.5			μ s
t_{HIGH}	SCL clock high time	0.26			μ s
$t_{SU,DAT}$	SDA set-up time	50			ns
$t_{HD,DAT}$	SDA hold time	8			ns
$t_{SU,STA}$	Repeated START condition set-up time	0.26			μ s
$t_{HD,STA}$	(Repeated) START condition hold time	0.26			μ s
$t_{SU,STO}$	STOP condition set-up time	0.26			μ s
t_{BUF}	Bus free time between a STOP and a START condition	0.5			μ s

¹For the minimum HPPERCLK frequency required in Fast-mode Plus, see the I2C chapter in the EFM32WG Reference Manual.

3.17 USART SPI

Figure 3.38. SPI Master Timing

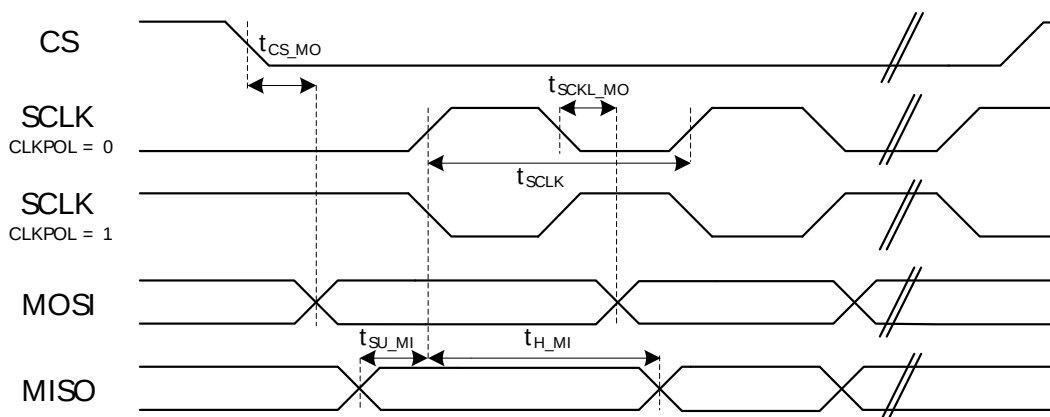


Table 3.24. SPI Master Timing

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{SCLK}^{1,2}$	SCLK period		$2 * t_{HPPER-CLK}$			ns
$t_{CS_MO}^{1,2}$	CS to MOSI		-2.00		2.00	ns
$t_{SCLK_MO}^{1,2}$	SCLK to MOSI		-1.00		3.00	ns
$t_{SU_MI}^{1,2}$	MISO setup time	IOVDD = 3.0 V	36.00			ns
$t_{H_MI}^{1,2}$	MISO hold time		-6.00			ns

¹Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)

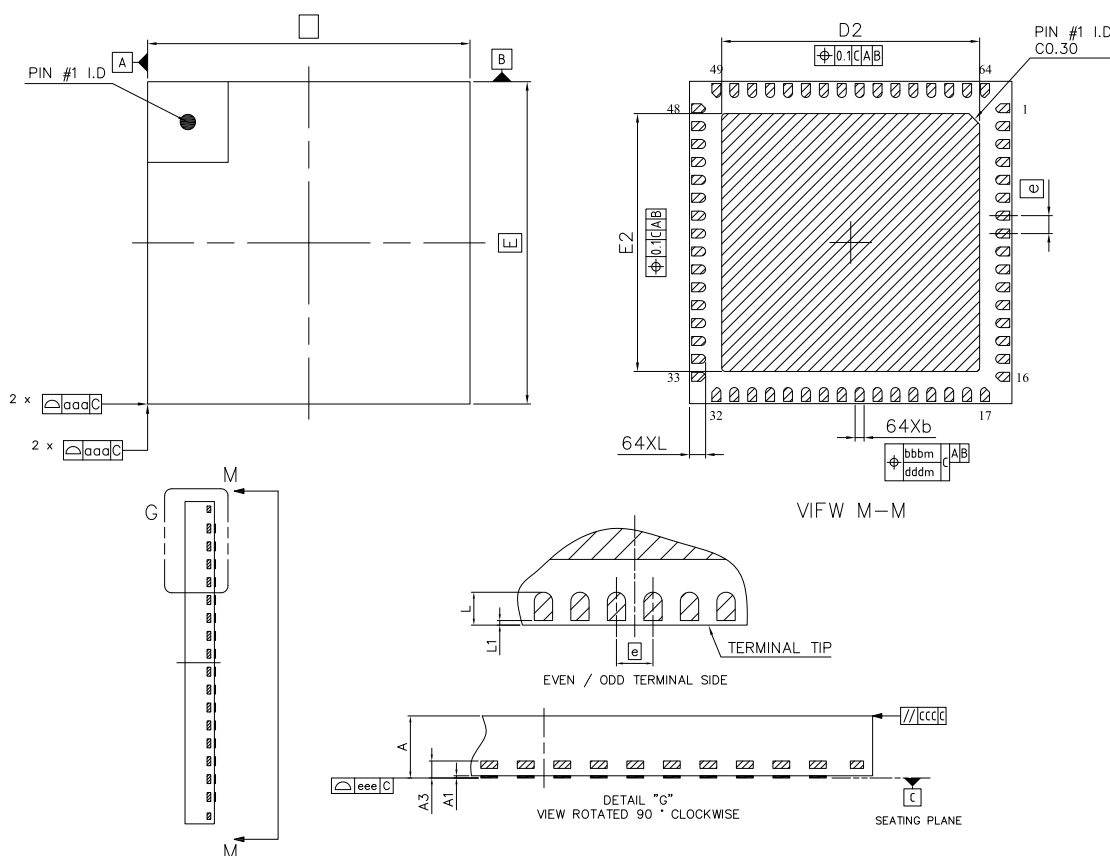
²Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG15	PA2							LCD segment line 15. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG16	PA3							LCD segment line 16. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG17	PA4							LCD segment line 17. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG19	PA6							LCD segment line 19. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LES_ALTEX0	PD6							LESENSE alternate exit output 0.
LES_ALTEX1	PD7							LESENSE alternate exit output 1.
LES_ALTEX2	PA3							LESENSE alternate exit output 2.
LES_ALTEX3	PA4							LESENSE alternate exit output 3.
LES_ALTEX4	PA5							LESENSE alternate exit output 4.
LES_ALTEX5	PE11							LESENSE alternate exit output 5.
LES_ALTEX6	PE12							LESENSE alternate exit output 6.
LES_ALTEX7	PE13							LESENSE alternate exit output 7.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
PCNT0_S0IN	PC13			PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14			PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2		PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3		PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0		PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1		PD2		PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2		PD3		PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13		PF3		Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14		PF4		Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0		PA12						Timer 2 Capture Compare input / output channel 0.
TIM2_CC1		PA13						Timer 2 Capture Compare input / output channel 1.
TIM2_CC2		PA14						Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14							Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	PE15							Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	PA15							Timer 3 Capture Compare input / output channel 2.
US0_CLK	PE12	PE5		PC15	PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4		PC14	PB14	PB14		USART0 chip select input / output.
US0_RX	PE11	PE6		PE12	PB8			USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7		PE13	PB7			USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX		PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX		PD0	PD7					USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.

4.5 QFN64 Package

Figure 4.3. QFN64



Rev: 98SPPG4048A_XO1_08MAR2011

Note:

1. Dimensioning & tolerancing confirm to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.
3. Dimension 'b' applies to metallized terminal and is measured between 0.25 mm and 0.30 mm from the terminal tip. Dimension L1 represents terminal full back from package edge up to 0.1 mm is acceptable.
4. Coplanarity applies to the exposed heat slug as well as the terminal.
5. Radius on terminal is optional

Table 4.4. QFN64 (Dimensions in mm)

Symbol	A	A1	A3	b	D	E	D2	E2	e	L	L1	aaa	bbb	ccc	ddd	eee
Min	0.80	0.00	0.203 REF	0.20	9.00 BSC	9.00 BSC	7.10	7.10	0.50 BSC	0.40	0.00	0.10	0.10	0.10	0.05	0.08
Nom	0.85	-		0.25			7.20	7.20		0.45						
Max	0.90	0.05		0.30			7.30	7.30		0.50	0.10					

The QFN64 Package uses Nickel-Palladium-Gold preplated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see:

<http://www.silabs.com/support/quality/pages/default.aspx>

5 PCB Layout and Soldering

5.1 Recommended PCB Layout

Figure 5.1. QFN64 PCB Land Pattern

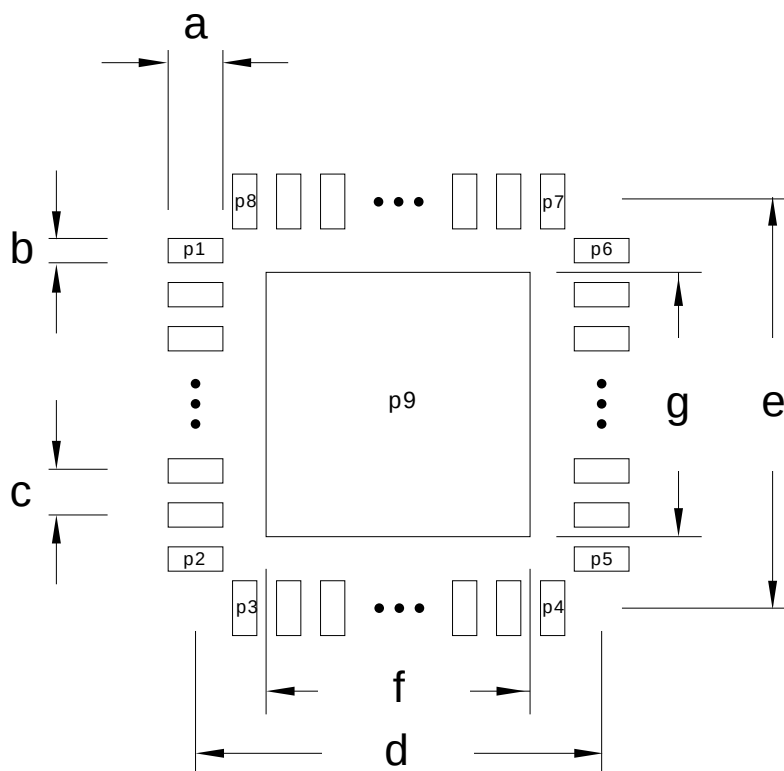


Table 5.1. QFN64 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin number	Symbol	Pin number
a	0.85	P1	1	P8	64
b	0.30	P2	16	P9	65
c	0.50	P3	17	-	-
d	8.90	P4	32	-	-
e	8.90	P5	33	-	-
f	7.20	P6	48	-	-
g	7.20	P7	49	-	-

Figure 5.2. QFN64 PCB Solder Mask

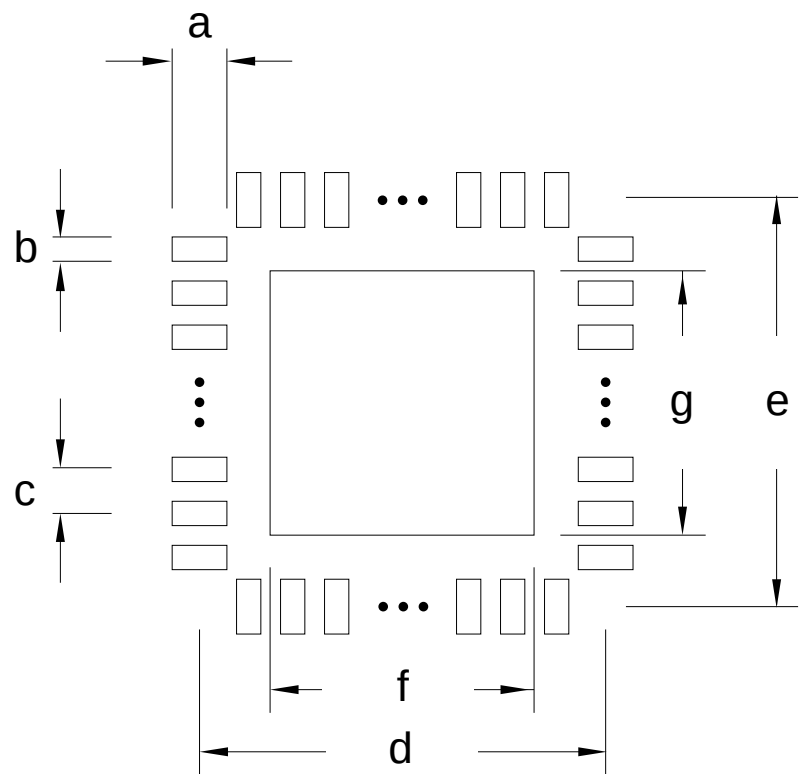


Table 5.2. QFN64 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Dim. (mm)
a	0.97	e	8.90
b	0.42	f	7.32
c	0.50	g	7.32
d	8.90	-	-

B Contact Information

Silicon Laboratories Inc.
400 West Cesar Chavez
Austin, TX 78701

Please visit the Silicon Labs Technical Support web page:
<http://www.silabs.com/support/pages/contacttechnicalsupport.aspx>
and register to submit a technical support request.

List of Equations

3.1. Total ACMP Active Current 47

3.2. VCMP Trigger Level as a Function of Level Setting 49

3.3. Total LCD Current Based on Operational Mode and Internal Boost 50